

MPF5030BMMA4ES – NXP Standard

Configuration report for QM OTP program ID: A4 rev B

Rev. 1.0 - 08/03/2023

Report

1 General description

The PF5030 is a power management integrated circuit (PMIC) designed for S32Z2/E2 processors. Its input voltage up to 5.25 V maximum for automotive drive train market allows to be ideally attached to NXP front system supply families (FS86, FS6x) or any other front supply.

Built-in one-time programmable memory stores key startup configurations, drastically reducing external components typically used to set output voltage and sequence of external regulators. Regulator parameters are adjustable through high-speed I2C after startup, offering flexibility for different system states.

Note: Electrical characteristics for the PF5030 are maintained in the datasheet.

2 Features and benefits

Voltage Range

- 5 V DC maximum input voltage
- Support operating voltage range down to 3.3 V
- Low Power OFF mode with low sleep current (15 uA typ.)

Power Supplies

- BUCK1/2: Low voltage integrated synchronous BUCK converter
 - Configurable output voltage from 0.7 V to 1.5 V and current capability up to 3.5 A DC
 - Capable of multiphase operation for up to 7.0 A DC
- BUCK3: Low voltage integrated synchronous BUCK converter
 - Configurable output voltage from 1.0 V to 4.1 V and current capability up to 2.5 A DC
- LDO1/2: Low voltage LDO regulator for MCU I/O and system peripheral
 - Configurable Output voltage from 1.1 V to 4.1 V and current capability up to 400 mA DC

System support

- 1x input pins for power-ON detection, 1.8 V / 3.3 V / 5.0 V compatible
- Analog Multiplexer with full System Voltages monitoring
- Enhanced master/slave power up sequencing management thru XFAILB pin
- 10 ms optional RSTB release delay during power up for certain MCU compliancy
- Device control via 32 bits I2C 1 MHz interface with 8-bit CRC



Configuration report for QM OTP program ID: A4 rev B

Compliance

- EMC optimization techniques on switching regulators including spread spectrum
- EMI robustness supporting various automotive EMI Test standards
- Conducted Emission: IEC 61967-4
- Conducted Immunity: IEC 62132-4

Functional Safety

- ASILD capability on UV/OV for all S32Z2/E2 power rails (0.8 V, 1.1 V, 1.8 V and 3.3 V)
- Independent voltage Monitoring Circuitry
- Up to 6 voltage monitoring inputs for PF5030 and external voltage rails with 1 % target accuracy
- Logical and Analog Built-in Self-Test
- Safety Outputs with latent fault detection mechanism (PGOOD, RSTB, FS0B)

Configuration and Enablement

- QFN 40 pins with exposed pad for optimized thermal management
- OTP programming for device customization

3 Applications

- EV propulsion and Power train domain controller
- Chassis integrated systems
- S32Z2/E2 companion chip

4 Ordering information

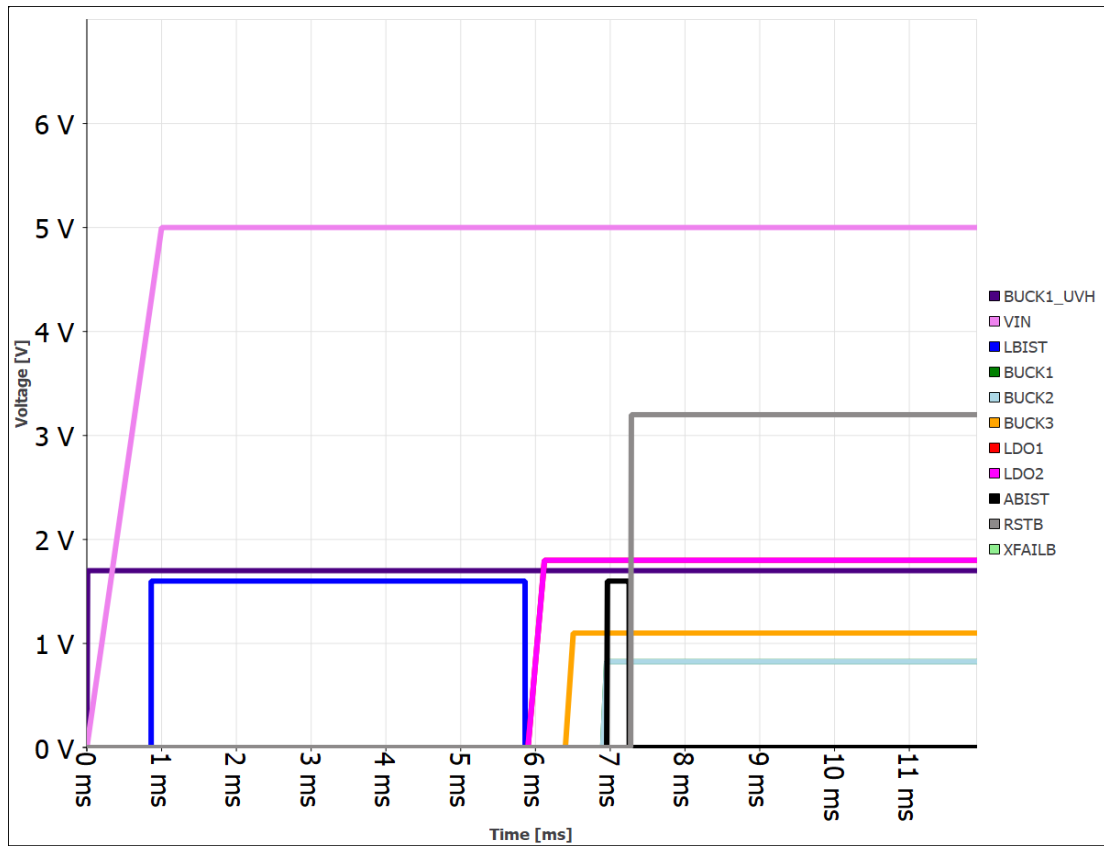
Table 1. Ordering information

Type number ^{[1][2]}	Package		
	Name	Description	Version
MPF5030BMMA4ES	QFN40eP	QFN40ep, plastic, thermally enhanced, wettable flanks, 6 x 6 x 0.85mm, 0.5 mm pitch, 40 pins	SOT618-18(D)

[1] To order parts in tape and reel, add the R2 suffix to the part number.

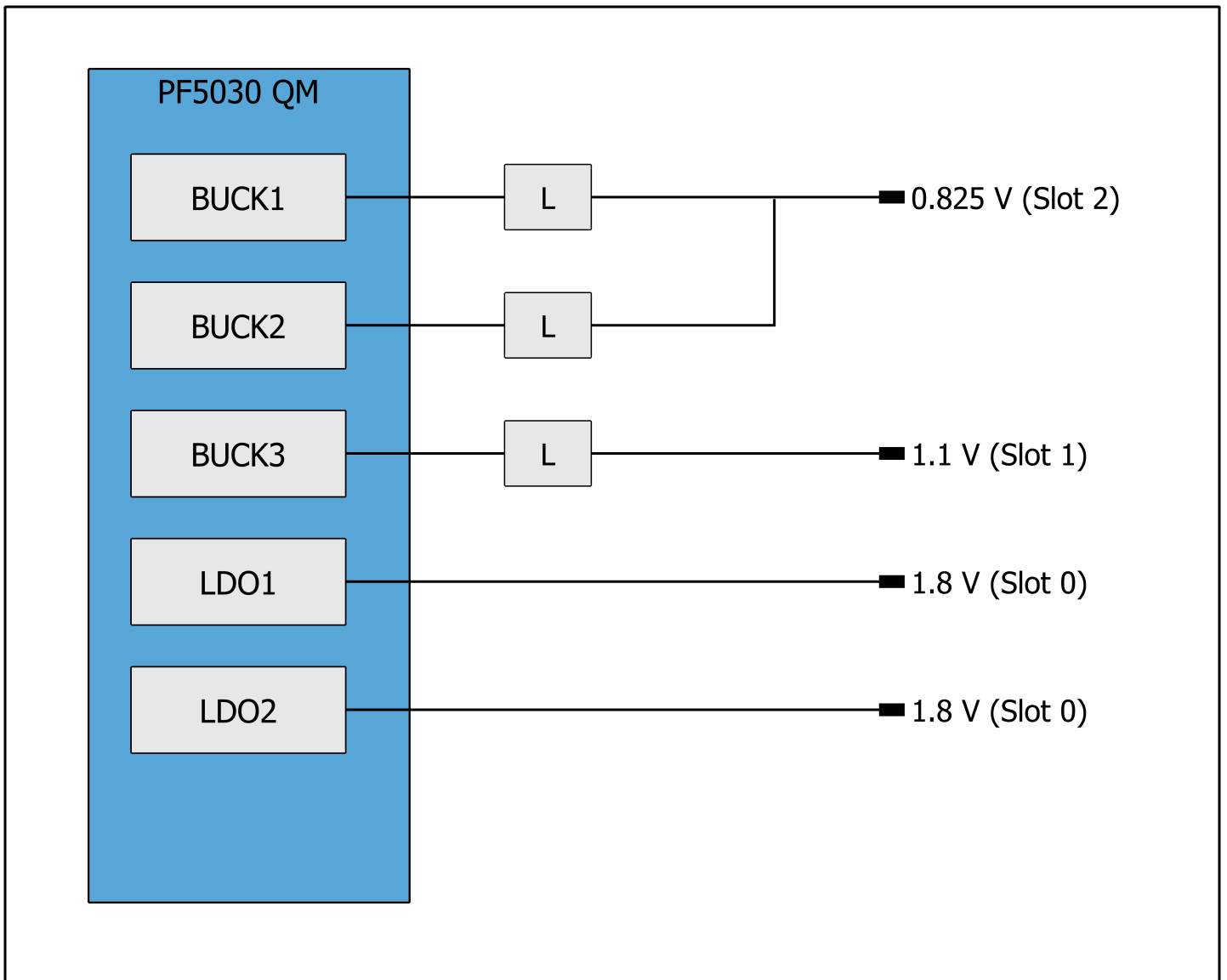
[2] For production part number use prefix S instead of P

5 Power-up sequence summary



The signals depicted above are enable signals for each regulator. They don't represent the actual ramp voltage.

6 Hardware configuration diagram



7 OTP configuration

See PF5030 datasheet for parametric details. The OTP configuration summary for A4 sequence ID is provided in Tables below.

Table 2. Main Configuration

Functional block	Feature	OTP selection
System configuration	Main Device I2C Address	0x22
	FailSafe Device I2C Address	0x23
	Device ID	1
	VIN Undervoltage Threshold	5.0 V (UV at 4.3 V)
	Power Down Sequence In Case Of DFS	Power down sequence
	Autoretry Enable Configuration	Enabled
	Autoretry Number Configuration	Endless
	Deglitcher Time SCL Signal	15 ns
	Delay Between Main State Machine	2 ms
	Program ID Low	4
	Program ID High	A
	VMON4 External Regulator Assign	LDO1
	VMON5 External Regulator Assign	LDO2
Clock and Synchronisation	Enable Clock Modulation	Clock modulation enabled
	Clock Modulation Configuration	Triangular modulation
	XFAILB Configuration	Synchronization enabled
	XFAILB Release Slot	Slot 0
	XFAILB Assertion Impact	Power down when XFAILB is asserted low

Configuration report for QM OTP program ID: A4 rev B

Table 3. Power-up sequence

Functional block	Feature	OTP selection
Power-up sequence	BUCK1 Power-up Slot	Slot 2
	BUCK2 Power-up Slot	Slot 2
	BUCK3 Power-up Slot	Slot 1
	LDO1 Power-up Slot	Slot 0
	LDO2 Power-up Slot	Slot 0
	Power-up/down Slot Timing	0.5 ms
	Power-up Last Slot	Power up ends in slot 3
	Power-down First Slot	Power down starts in slot 3

Table 4. Switching and LDOs regulators

Functional block	Feature	OTP selection
BUCK1/2 multiphase operation	BUCK1 And BUCK2 Multiphase Operation	Enabled
	DVS Ramp Of BUCK1/2	15.62 mV/us
BUCK1 configuration	BUCK1 Inductor Selection	0.47 uH
	BUCK1 Output Voltage	0.825 V
	BUCK1 Transconductance	2.91
	BUCK1 Current Limitation	5 A
	BUCK1 Phase Delay	No delay
	BUCK1 TSD Behavior	BUCK1 shutdown
BUCK2 configuration	BUCK2 Enable	Enabled
	BUCK2 Inductor Selection	0.47 uH
	BUCK2 Output Voltage	0.825 V
	BUCK2 Transconductance	2.91

Configuration report for QM OTP program ID: A4 rev B

	BUCK2 Current Limitation	5 A
	BUCK2 Phase Delay	Delay 4
	BUCK2 TSD Behavior	BUCK2 shutdown
BUCK3 configuration	BUCK3 Enable	Enabled
	BUCK3 Inductor Selection	1 uH
	BUCK3 Output Voltage	1.1 V
	BUCK3 Current Limitation	2.1 A
	BUCK3 Phase Delay	Delay 3
	BUCK3 TSD Behavior	BUCK3 shutdown
	BUCK3 Soft Start Ramp	10.41 mV/us
LDO1 configuration	LDO1 Load Switch Mode Enable	Disabled
	LDO1 Output Voltage	1.8 V
	LDO1 TSD Behavior	LDO1 shutdown
LDO2 configuration	LDO2 Load Switch Mode Enable	Disabled
	LDO2 Output Voltage	1.8 V
	LDO2 TSD Behavior	LDO2 shutdown

Table 5. System safety configuration

Functional block	Feature	OTP selection
System safety configuration	Watchdog Infinite Window	Infinite open window
	Watchdog Mode Selection	Simple watchdog
	RSTb 8s Timer Disable	Counter enabled
	RSTB Delay	No delay

Configuration report for QM OTP program ID: A4 rev B

	RSTB Pgood	Fault asserting RSTb will assert PGOOD
	Revert Backup Safety Path	Enabled
	SVS Max Value Allowed	No SVS

Table 6. Voltage monitoring

Functional block	Feature	OTP selection
VMON0 configuration	VMON0 Enable	Enabled
	VMON0 Undervoltage Threshold	96.0 %
	VMON0 Overvoltage Threshold	104.0 %
	VMON0 Undervoltage Deglitcher	100us/400 us
	VMON0 Overvoltage Deglitcher	100 us/400 us
	VMON0 Assignment To PGOOD	Not assigned
	VMON0 Assignment To ABIST1	Assigned
VMON1 configuration	VMON1 Enable	Enabled
	VMON1 Voltage Configuration	0.825 V
	VMON1 Undervoltage Threshold	96.0 %
	VMON1 Overvoltage Threshold	104.0 %
	VMON1 Undervoltage Deglitcher	100 us/400 us
	VMON1 Overvoltage Deglitcher	100 us/400 us
	VMON1 Assignment To PGOOD	Not assigned
VMON1 Assignment To ABIST1	Assigned	
VMON2 configuration	VMON2 Enable	Enabled
	VMON2 Voltage Configuration	0.875 V
	VMON2 Undervoltage Threshold	90.0 %
	VMON2 Overvoltage Threshold	110.0 %

Configuration report for QM OTP program ID: A4 rev B

	VMON2 Undervoltage Deglitcher	100 us/400 us
	VMON2 Overvoltage Deglitcher	100 us/400 us
	VMON2 Assignment To PGOOD	Not assigned
	VMON2 Assignment To ABIST1	Assigned
VMON3 configuration	VMON3 Enable	Enabled
	VMON3 Voltage Configuration	1.1 V
	VMON3 Undervoltage Threshold	97.5 %
	VMON3 Overvoltage Threshold	104.0 %
	VMON3 Undervoltage Deglitcher	100 us/400 us
	VMON3 Overvoltage Deglitcher	100 us/400 us
	VMON3 Assignment To PGOOD	Not assigned
	VMON3 Assignment To ABIST1	Assigned
VMON4 configuration	VMON4 Enable	Enabled
	VMON4 Voltage Configuration	1.8 V
	VMON4 Undervoltage Threshold	95.5 %
	VMON4 Overvoltage Threshold	104.5 %
	VMON4 Undervoltage Deglitcher	100 us/400 us
	VMON4 Overvoltage Deglitcher	100 us/400 us
	VMON4 Assignment To PGOOD	Not assigned
	VMON4 Assignment To ABIST1	Assigned
VMON5 configuration	VMON5 Enable	Enabled
	VMON5 Voltage Configuration	1.8 V
	VMON5 Undervoltage Threshold	95.5 %
	VMON5 Overvoltage Threshold	104.5 %

Configuration report for QM OTP program ID: A4 rev B

	VMON5 Undervoltage Deglitcher	100 us/400 us
	VMON5 Overvoltage Deglitcher	100 us/400 us
	VMON5 Assignment To PGOOD	Not assigned
	VMON5 Assignment To ABIST1	Assigned

8 Legal information

8.1 Definitions

Draft - The document is a draft version only. The content is still under internal review and subject to formal approval, which may result in modifications or additions. NXP Semiconductors does not give any representations or warranties as to the accuracy or completeness of information included herein and shall have no liability for the consequences of use of such information.

Limited warranty and liability - Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors. In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory. Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes - NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

Suitability for use - NXP Semiconductors products are not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Applications - Applications that are described herein for any of these products are for illustrative purposes only. NXP Semiconductors makes no representation or warranty that such applications will be suitable for the specified use without further testing or modification. Customers are responsible for the design and operation of their applications and products using NXP Semiconductors products, and NXP Semiconductors accepts no liability for any assistance with applications or customer product design. It is customer's sole responsibility to determine whether the NXP Semiconductors product is suitable and fit for the customer's applications and products planned, as well as for the planned application and use of customer's third party customer(s). Customers should provide appropriate design and operating safeguards to minimize the risks associated with their applications and products. NXP Semiconductors does not accept any liability related to any default, damage, costs or problem

which is based on any weakness or default in the customer's applications or products, or the application or use by customer's third party customer(s). Customer is responsible for doing all necessary testing for the customer's applications and products using NXP Semiconductors products in order to avoid a default of the applications and the products or of the application or use by customer's third party customer(s). NXP does not accept any liability in this respect.

Limiting values - Stress above one or more limiting values (as defined in the Absolute Maximum Ratings System of IEC 60134) will cause permanent damage to the device. Limiting values are stress ratings only and (proper) operation of the device at these or any other conditions above those given in the Recommended operating conditions section (if present) or the Characteristics sections of this document is not warranted. Constant or repeated exposure to limiting values will permanently and irreversibly affect the quality and reliability of the device.

Terms and conditions of commercial sale - NXP Semiconductors products are sold subject to the general terms and conditions of commercial sale, as published at <http://www.nxp.com/profile/terms>, unless otherwise agreed in a valid written individual agreement. In case an individual agreement is concluded only the terms and conditions of the respective agreement shall apply. NXP Semiconductors here by expressly objects to applying the customer's general terms and conditions with regard to the purchase of NXP Semiconductors products by customer.

No offer to sell or license - Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.

Suitability for use in automotive applications - This NXP Semiconductors product has been qualified for use in automotive applications. Unless otherwise agreed in writing, the product is not designed, authorized or warranted to be suitable for use in life support, life-critical or safety-critical systems or equipment, nor in applications where failure or malfunction of an NXP Semiconductors product can reasonably be expected to result in personal injury, death or severe property or environmental damage. NXP Semiconductors and its suppliers accept no liability for inclusion and/or use of NXP Semiconductors products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

Export control - This document as well as the item(s) described herein may be subject to export control regulations. Export might require a prior authorization from competent authorities.

Translations - A non-English (translated) version of a document is for reference only. The English version shall prevail in case of any discrepancy between the translated and English versions.

8.2 Trademarks

Notice: All referenced brands, product names, service names and trademarks are the property of their respective owners.

NXP - is a trademark of NXP B.V.

Contents

1 General description	1
2 Features and benefits	1
3 Applications	1
4 Ordering information	2
5 Power up sequence summary	2
6 Hardware configuration diagram	3
7 OTP configuration	5
8 Legal information	11

Please be aware that important notices concerning this document and the product(s) described herein, have been included in section 'Legal information'.

© NXP B.V. 2023 .

All rights reserved.

For more information, please visit: <http://www.nxp.com>

For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 08/03/2023

Document identifier: R_MPF5030BMMA4ES